IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Makoto Yoshino, et al.

Docket:

TIJ-29448

Serial No.:

TBD

Examiner:

TBD

Filed:

Herewith

Art Unit:

TBD

For:

SEMICONDUCTOR PACKAGE INSULATION FILM AND MANUFACTURING

METHOD THEREOF

PRELIMINARY AMENDMENT

Assistant Commissioner For Patents Washington, D. C. 20231

Sir:

"EXPRESS MAIL" mailing label number EL645450686US, Date of Deposit: : 19 July 2001.

I hereby certify that the Preliminary Amendment and the accompanying Application is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 § CFR 1.10 on the above-mentioned date and is addressed to the Assistant Commissioner of Patents, Box New Applications, Washington, DC 20231.

Allen B. Kroger

Before examination of the above-identified patent application, please make the following amendments:

IN THE CLAIMS:

Please amend claims 1-11 as follows:

1. (Amended) An insulation film for providing an insulation substrate for carrying a semiconductor chip of a semiconductor package comprising: